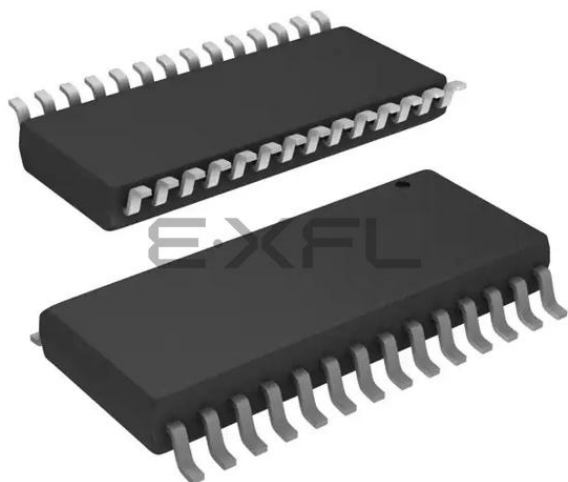




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Details

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	32MHz
Connectivity	I ² C, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	25
Program Memory Size	7KB (4K x 14)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	512 x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 17x10b; D/A 1x5b, 1x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SOIC (0.295", 7.50mm Width)
Supplier Device Package	28-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lf1713-i-so

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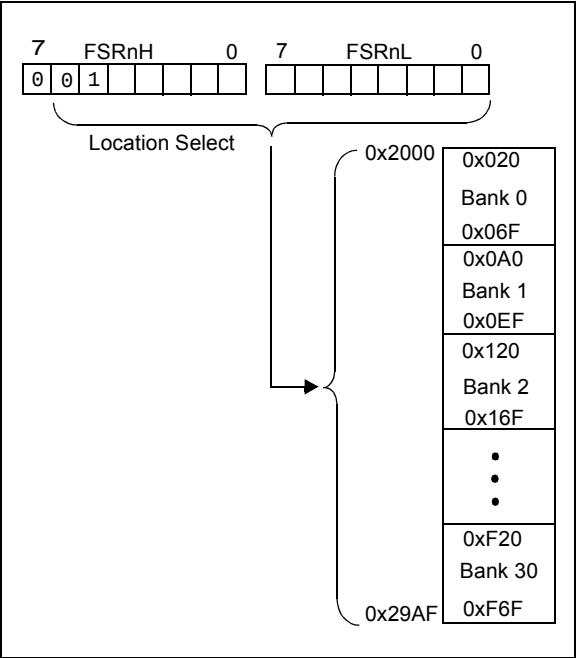
3.7.2 LINEAR DATA MEMORY

The linear data memory is the region from FSR address 0x2000 to FSR address 0x29AF. This region is a virtual region that points back to the 80-byte blocks of GPR memory in all the banks.

Unimplemented memory reads as 0x00. Use of the linear data memory region allows buffers to be larger than 80 bytes because incrementing the FSR beyond one bank will go directly to the GPR memory of the next bank.

The 16 bytes of common memory are not included in the linear data memory region.

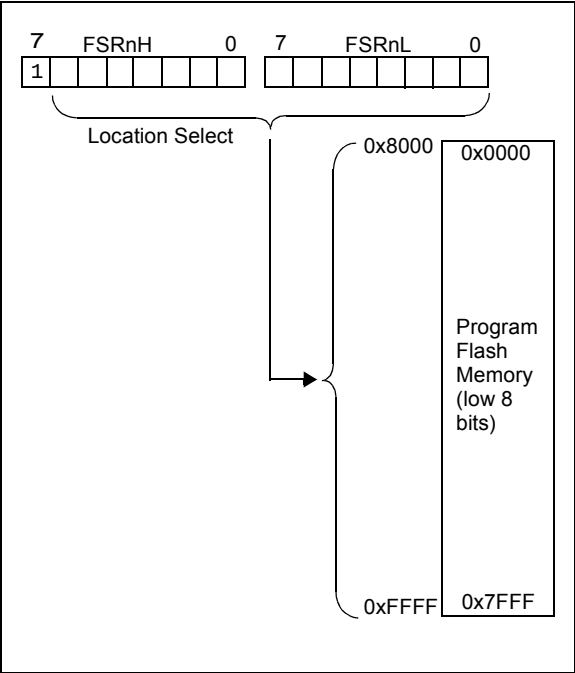
FIGURE 3-11: LINEAR DATA MEMORY MAP



3.7.3 PROGRAM FLASH MEMORY

To make constant data access easier, the entire program Flash memory is mapped to the upper half of the FSR address space. When the MSB of FSRnH is set, the lower 15 bits are the address in program memory which will be accessed through INDF. Only the lower eight bits of each memory location is accessible via INDF. Writing to the program Flash memory cannot be accomplished via the FSR/INDF interface. All instructions that access program Flash memory via the FSR/INDF interface will require one additional instruction cycle to complete.

FIGURE 3-12: PROGRAM FLASH MEMORY MAP



4.2 Register Definitions: Configuration Words

REGISTER 4-1: CONFIG1: CONFIGURATION WORD 1

R/P-1	R/P-1	R/P-1	R/P-1	R/P-1	U-1
FCMEN	IESO	CLKOUTEN	BOREN<1:0>	—	
bit 13					bit 8

R/P-1	R/P-1	R/P-1	R/P-1	R/P-1	R/P-1	R/P-1	R/P-1
CP ⁽¹⁾	MCLRE	PWRT	WDTE<1:0>	FOSC<2:0>			
bit 7							bit 0

Legend:

R = Readable bit P = Programmable bit U = Unimplemented bit, read as '1'
 '0' = Bit is cleared '1' = Bit is set -n = Value when blank or after Bulk Erase

- bit 13 **FCMEN:** Fail-Safe Clock Monitor Enable bit
 1 = Fail-Safe Clock Monitor and internal/external switchover are both enabled.
 0 = Fail-Safe Clock Monitor is disabled
- bit 12 **IESO:** Internal External Switchover bit
 1 = Internal/External Switchover mode is enabled
 0 = Internal/External Switchover mode is disabled
- bit 11 **CLKOUTEN:** Clock Out Enable bit
If FOSC configuration bits are set to LP, XT, HS modes:
 This bit is ignored, CLKOUT function is disabled. Oscillator function on the CLKOUT pin.
All other FOSC modes:
 1 = CLKOUT function is disabled. I/O function on the CLKOUT pin.
 0 = CLKOUT function is enabled on the CLKOUT pin
- bit 10-9 **BOREN<1:0>:** Brown-out Reset Enable bits
 11 = BOR enabled
 10 = BOR enabled during operation and disabled in Sleep
 01 = BOR controlled by SBOREN bit of the BORCON register
 00 = BOR disabled
- bit 8 **Unimplemented:** Read as '1'
- bit 7 **CP:** Code Protection bit⁽¹⁾
 1 = Program memory code protection is disabled
 0 = Program memory code protection is enabled
- bit 6 **MCLRE:** MCLR/VPP Pin Function Select bit
If LVP bit = 1:
 This bit is ignored.
If LVP bit = 0:
 1 = MCLR/VPP pin function is MCLR; Weak pull-up enabled.
 0 = MCLR/VPP pin function is digital input; MCLR internally disabled; Weak pull-up under control of WPUE3 bit.
- bit 5 **PWRT:** Power-up Timer Enable bit
 1 = PWRT disabled
 0 = PWRT enabled
- bit 4-3 **WDTE<1:0>:** Watchdog Timer Enable bit
 11 = WDT enabled
 10 = WDT enabled while running and disabled in Sleep
 01 = WDT controlled by the SWDTEN bit in the WDTCON register
 00 = WDT disabled

TABLE 5-5: SUMMARY OF REGISTERS ASSOCIATED WITH RESETS

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
BORCON	SBOREN	BORFS	—	—	—	—	—	BORRDY	54
PCON	STKOVF	STKUNF	—	$\overline{\text{RWDT}}$	$\overline{\text{RMCLR}}$	$\overline{\text{RI}}$	$\overline{\text{POR}}$	$\overline{\text{BOR}}$	58
STATUS	—	—	—	$\overline{\text{TO}}$	$\overline{\text{PD}}$	Z	DC	C	19
WDTCON	—	—	WDTPS<4:0>					SWDTEN	98

Legend: — = unimplemented location, read as '0'. Shaded cells are not used by Resets.

6.0 OSCILLATOR MODULE (WITH FAIL-SAFE CLOCK MONITOR)

6.1 Overview

The oscillator module has a wide variety of clock sources and selection features that allow it to be used in a wide range of applications while maximizing performance and minimizing power consumption. Figure 6-1 illustrates a block diagram of the oscillator module.

Clock sources can be supplied from external oscillators, quartz crystal resonators, ceramic resonators and Resistor-Capacitor (RC) circuits. In addition, the system clock source can be supplied from one of two internal oscillators and PLL circuits, with a choice of speeds selectable via software. Additional clock features include:

- Selectable system clock source between external or internal sources via software.
- Two-Speed Start-up mode, which minimizes latency between external oscillator start-up and code execution.
- Fail-Safe Clock Monitor (FSCM) designed to detect a failure of the external clock source (LP, XT, HS, ECH, ECM, ECL or EXTRC modes) and switch automatically to the internal oscillator.
- Oscillator Start-up Timer (OST) ensures stability of crystal oscillator sources.

The oscillator module can be configured in one of the following clock modes.

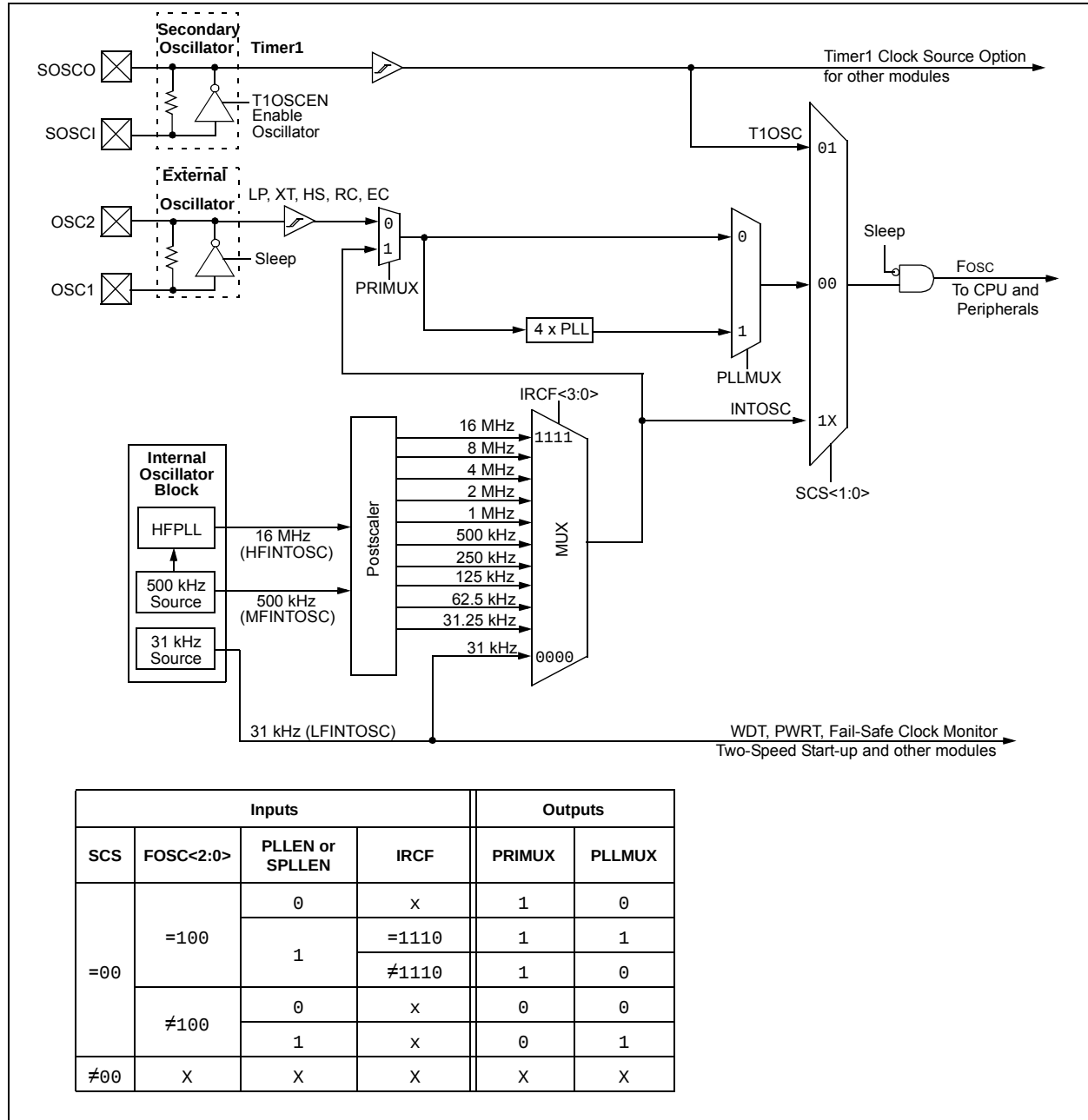
1. ECL – External Clock Low-Power mode (0 MHz to 0.5 MHz)
2. ECM – External Clock Medium Power mode (0.5 MHz to 4 MHz)
3. ECH – External Clock High-Power mode (4 MHz to 32 MHz)
4. LP – 32 kHz Low-Power Crystal mode.
5. XT – Medium Gain Crystal or Ceramic Resonator Oscillator mode (up to 4 MHz)
6. HS – High Gain Crystal or Ceramic Resonator mode (4 MHz to 20 MHz)
7. EXTRC – External Resistor-Capacitor
8. INTOSC – Internal oscillator (31 kHz to 32 MHz)

Clock Source modes are selected by the FOSC<2:0> bits in the Configuration Words. The FOSC bits determine the type of oscillator that will be used when the device is first powered.

The ECH, ECM, and ECL clock modes rely on an external logic level signal as the device clock source. The LP, XT, and HS clock modes require an external crystal or resonator to be connected to the device. Each mode is optimized for a different frequency range. The EXTRC clock mode requires an external resistor and capacitor to set the oscillator frequency.

The INTOSC internal oscillator block produces low, medium, and high-frequency clock sources, designated LFINTOSC, MFINTOSC and HFINTOSC. (see Internal Oscillator Block, Figure 6-1). A wide selection of device clock frequencies may be derived from these three clock sources.

FIGURE 6-1: SIMPLIFIED PIC® MCU CLOCK SOURCE BLOCK DIAGRAM



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6.2.1.4 4x PLL

The oscillator module contains a 4x PLL that can be used with both external and internal clock sources to provide a system clock source. The input frequency for the 4x PLL must fall within specifications. See the PLL Clock Timing Specifications in Table 34-9.

The 4x PLL may be enabled for use by one of two methods:

1. Program the PLEN bit in Configuration Words to a '1'.
2. Write the SPLLEN bit in the OSCCON register to a '1'. If the PLEN bit in Configuration Words is programmed to a '1', then the value of SPLLEN is ignored.

6.2.1.5 Secondary Oscillator

The secondary oscillator is a separate crystal oscillator that is associated with the Timer1 peripheral. It is optimized for timekeeping operations with a 32.768 kHz crystal connected between the SOSCO and SOSCI device pins.

The secondary oscillator can be used as an alternate system clock source and can be selected during run-time using clock switching. Refer to **Section 6.3 "Clock Switching"** for more information.

Note 1: Quartz crystal characteristics vary according to type, package and manufacturer. The user should consult the manufacturer data sheets for specifications and recommended application.

2: Always verify oscillator performance over the VDD and temperature range that is expected for the application.

3: For oscillator design assistance, reference the following Microchip Application Notes:

- AN826, "Crystal Oscillator Basics and Crystal Selection for *rfPIC*® and *PIC*® Devices" (DS00826)
- AN849, "Basic *PIC*® Oscillator Design" (DS00849)
- AN943, "Practical *PIC*® Oscillator Analysis and Design" (DS00943)
- AN949, "Making Your Oscillator Work" (DS00949)
- TB097, "Interfacing a Micro Crystal MS1V-T1K 32.768 kHz Tuning Fork Crystal to a *PIC16F690/SS*" (DS91097)
- AN1288, "Design Practices for Low-Power External Oscillators" (DS01288)

FIGURE 6-5: QUARTZ CRYSTAL OPERATION (SECONDARY OSCILLATOR)

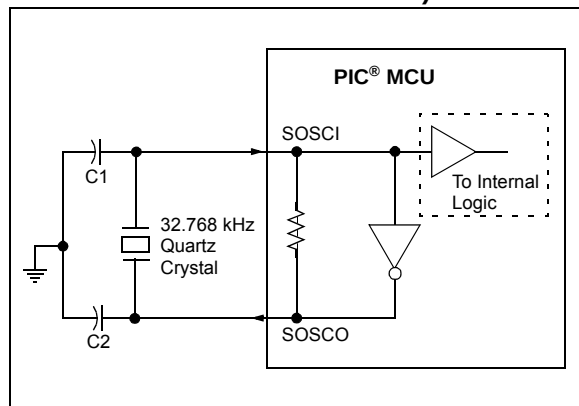


TABLE 9-3: SUMMARY OF REGISTERS ASSOCIATED WITH WATCHDOG TIMER

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
OSCCON	SPLLEN	IRCF<3:0>				—	SCS<1:0>		75
STATUS	—	—	—	$\overline{TO}$	$\overline{PD}$	Z	DC	C	19
WDTCON	—	—	WDTPS<4:0>					SWDTEN	98

Legend: x = unknown, u = unchanged, — = unimplemented locations read as '0'. Shaded cells are not used by Watchdog Timer.

TABLE 9-4: SUMMARY OF CONFIGURATION WORD WITH WATCHDOG TIMER

Name	Bits	Bit -/7	Bit -/6	Bit 13/5	Bit 12/4	Bit 11/3	Bit 10/2	Bit 9/1	Bit 8/0	Register on Page
CONFIG1	13:8	—	—	FCMEN	IESO	CLKOUTEN	BOREN<1:0>		—	47
	7:0	CP	MCLRE	PWRTE	WDTE<1:0>		FOSC<2:0>			

Legend: — = unimplemented location, read as '0'. Shaded cells are not used by Watchdog Timer.

17.1.5 PWM RESOLUTION

The resolution determines the number of available duty cycles for a given period. For example, a 10-bit resolution will result in 1024 discrete duty cycles, whereas an 8-bit resolution will result in 256 discrete duty cycles.

The maximum PWM resolution is 10 bits when PR2 is 255. The resolution is a function of the PR2 register value as shown by Equation 17-4.

EQUATION 17-4: PWM RESOLUTION

$$\text{Resolution} = \frac{\log[4(\text{PR2} + 1)]}{\log(2)} \text{ bits}$$

Note: If the pulse width value is greater than the period the assigned PWM pin(s) will remain unchanged.

TABLE 17-1: EXAMPLE PWM FREQUENCIES AND RESOLUTIONS (Fosc = 20 MHz)

PWM Frequency	0.31 kHz	4.88 kHz	19.53 kHz	78.12 kHz	156.3 kHz	208.3 kHz
Timer Prescale	64	4	1	1	1	1
PR2 Value	0xFF	0xFF	0xFF	0x3F	0x1F	0x17
Maximum Resolution (bits)	10	10	10	8	7	6.6

TABLE 17-2: EXAMPLE PWM FREQUENCIES AND RESOLUTIONS (Fosc = 8 MHz)

PWM Frequency	0.31 kHz	4.90 kHz	19.61 kHz	76.92 kHz	153.85 kHz	200.0 kHz
Timer Prescale	64	4	1	1	1	1
PR2 Value	0x65	0x65	0x65	0x19	0x0C	0x09
Maximum Resolution (bits)	8	8	8	6	5	5

17.1.6 OPERATION IN SLEEP MODE

In Sleep mode, the TMR2 register will not increment and the state of the module will not change. If the PWMx pin is driving a value, it will continue to drive that value. When the device wakes up, TMR2 will continue from its previous state.

17.1.7 CHANGES IN SYSTEM CLOCK FREQUENCY

The PWM frequency is derived from the system clock frequency (Fosc). Any changes in the system clock frequency will result in changes to the PWM frequency. Refer to **Section 6.0 “Oscillator Module (with Fail-Safe Clock Monitor)”** for additional details.

17.1.8 EFFECTS OF RESET

Any Reset will force all ports to Input mode and the PWM registers to their Reset states.

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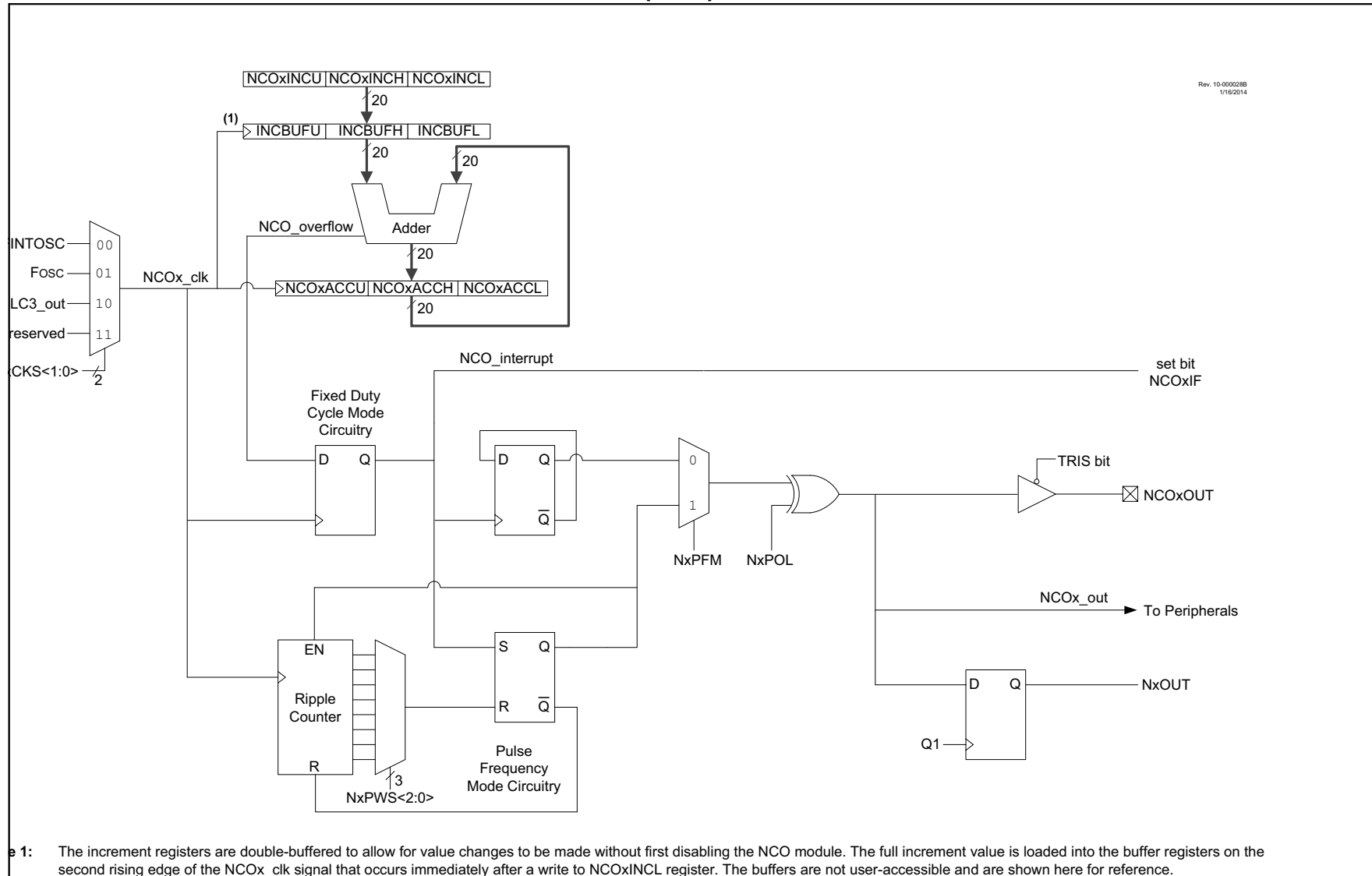


TABLE 20-1: SUMMARY OF REGISTERS ASSOCIATED WITH NCOx

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
INTCON	GIE	PEIE	TMR0IE	INTE	IOCFE	TMR0IF	INTF	IOCF	83
NCO1ACCU	—				NCO1ACC<19:16>				225
NCO1ACCH	NCO1ACC<15:8>								225
NCO1ACCL	NCO1ACC<7:0>								225
NCO1CLK	N1PWS<2:0>			—	—	—	N1CKS<1:0>		224
NCO1CON	N1EN	—	N1OUT	N1POL	—	—	—	N1PFM	224
NCO1INCUI	—				NCO1INC<19:16>				226
NCO1INCH	NCO1INC<15:8>								226
NCO1INCL	NCO1INC<7:0>								226
PIE3	—	NCOIE	COGIE	ZCDIE	CLC4IE	CLC3IE	CLC2IE	CLC1IE	86
PIR3	—	NCOIF	COGIF	ZCDIF	CLC4IF	CLC3IF	CLC2IF	CLC1IF	89
TRISA	TRISA7	TRISA6	TRISA5	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	119
TRISC	TRISC7	TRISC6	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0	130
RxyPPS	—	—	—	RxyPPS<4:0>					137

Legend: x = unknown, u = unchanged, — = unimplemented read as '0', q = value depends on condition. Shaded cells are not used for NCOx module.

21.2 ADC Operation

21.2.1 STARTING A CONVERSION

To enable the ADC module, the ADON bit of the ADCON0 register must be set to a '1'. Setting the GO/DONE bit of the ADCON0 register to a '1' will start the Analog-to-Digital conversion.

Note: The GO/DONE bit should not be set in the same instruction that turns on the ADC. Refer to **Section 21.2.6 “ADC Conversion Procedure”**.

21.2.2 COMPLETION OF A CONVERSION

When the conversion is complete, the ADC module will:

- Clear the GO/DONE bit
- Set the ADIF Interrupt Flag bit
- Update the ADRESH and ADRESL registers with new conversion result

21.2.3 TERMINATING A CONVERSION

If a conversion must be terminated before completion, the GO/DONE bit can be cleared in software. The ADRESH and ADRESL registers will be updated with the partially complete Analog-to-Digital conversion sample. Incomplete bits will match the last bit converted.

Note: A device Reset forces all registers to their Reset state. Thus, the ADC module is turned off and any pending conversion is terminated.

21.2.4 ADC OPERATION DURING SLEEP

The ADC module can operate during Sleep. This requires the ADC clock source to be set to the FRC option. When the FRC oscillator source is selected, the ADC waits one additional instruction before starting the conversion. This allows the SLEEP instruction to be executed, which can reduce system noise during the conversion. If the ADC interrupt is enabled, the device will wake-up from Sleep when the conversion completes. If the ADC interrupt is disabled, the ADC module is turned off after the conversion completes, although the ADON bit remains set.

When the ADC clock source is something other than FRC, a SLEEP instruction causes the present conversion to be aborted and the ADC module is turned off, although the ADON bit remains set.

21.2.5 AUTO-CONVERSION TRIGGER

The Auto-conversion Trigger allows periodic ADC measurements without software intervention. When a rising edge of the selected source occurs, the GO/DONE bit is set by hardware.

The Auto-conversion Trigger source is selected with the TRIGSEL<3:0> bits of the ADCON2 register.

Using the Auto-conversion Trigger does not assure proper ADC timing. It is the user's responsibility to ensure that the ADC timing requirements are met.

See Table 21-2 for auto-conversion sources.

TABLE 21-2: AUTO-CONVERSION SOURCES

Source Peripheral	Signal Name
CCP1	
CCP2	
Timer0	T0_overflow
Timer1	T1_overflow
Timer2	T2_match
Timer4	T4_match
Timer6	T6_match
Comparator C1	sync_C1OUT
Comparator C2	sync_C2OUT
CLC1	LC1_out
CLC2	LC2_out
CLC3	LC3_out
CLC4	LC4_out

21.4 ADC Acquisition Requirements

For the ADC to meet its specified accuracy, the charge holding capacitor (CHOLD) must be allowed to fully charge to the input channel voltage level. The Analog Input model is shown in Figure 21-4. The source impedance (Rs) and the internal sampling switch (RSS) impedance directly affect the time required to charge the capacitor CHOLD. The sampling switch (RSS) impedance varies over the device voltage (VDD), refer to Figure 21-4. **The maximum recommended impedance for analog sources is 10 kΩ.** As the

source impedance is decreased, the acquisition time may be decreased. After the analog input channel is selected (or changed), an ADC acquisition must be done before the conversion can be started. To calculate the minimum acquisition time, Equation 21-1 may be used. This equation assumes that 1/2 LSB error is used (1,024 steps for the ADC). The 1/2 LSB error is the maximum error allowed for the ADC to meet its specified resolution.

EQUATION 21-1: ACQUISITION TIME EXAMPLE

Assumptions: Temperature = 50°C and external impedance of 10kΩ 5.0V VDD

$$\begin{aligned} T_{ACQ} &= \text{Amplifier Settling Time} + \text{Hold Capacitor Charging Time} + \text{Temperature Coefficient} \\ &= T_{AMP} + T_C + T_{COFF} \\ &= 2\mu s + T_C + [(Temperature - 25^\circ C)(0.05\mu s/^\circ C)] \end{aligned}$$

The value for TC can be approximated with the following equations:

$$V_{APPLIED} \left(1 - \frac{1}{(2^{n+1}) - 1} \right) = V_{CHOLD} \quad ;[1] \text{ } V_{CHOLD} \text{ charged to within } 1/2 \text{ lsb}$$

$$V_{APPLIED} \left(1 - e^{\frac{-T_C}{RC}} \right) = V_{CHOLD} \quad ;[2] \text{ } V_{CHOLD} \text{ charge response to } V_{APPLIED}$$

$$V_{APPLIED} \left(1 - e^{\frac{-T_C}{RC}} \right) = V_{APPLIED} \left(1 - \frac{1}{(2^{n+1}) - 1} \right) \quad ;\text{combining [1] and [2]}$$

Note: Where n = number of bits of the ADC.

Solving for TC:

$$\begin{aligned} T_C &= -CHOLD(RIC + RSS + RS) \ln(1/2047) \\ &= -10pF(1k\Omega + 7k\Omega + 10k\Omega) \ln(0.0004885) \\ &= 1.37\mu s \end{aligned}$$

Therefore:

$$\begin{aligned} T_{ACQ} &= 2\mu s + 892ns + [(50^\circ C - 25^\circ C)(0.05\mu s/^\circ C)] \\ &= 4.62\mu s \end{aligned}$$

Note 1: The reference voltage (VREF) has no effect on the equation, since it cancels itself out.

2: The charge holding capacitor (CHOLD) is not discharged after each conversion.

3: The maximum recommended impedance for analog sources is 10 kΩ. This is required to meet the pin leakage specification.

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The MSSP consists of a transmit/receive shift register (SSPSR) and a buffer register (SSPBUF). The SSPSR shifts the data in and out of the device, MSb first. The SSPBUF holds the data that was written to the SSPSR until the received data is ready. Once the eight bits of data have been received, that byte is moved to the SSPBUF register. Then, the Buffer Full Detect bit, BF of the SSPSTAT register, and the interrupt flag bit, SSPIF, are set. This double-buffering of the received data (SSPBUF) allows the next byte to start reception before reading the data that was just received. Any write to the SSPBUF register during transmission/reception of data will be ignored and the write collision detect bit WCOL of the SSPCON1 register, will be set. User software must clear the WCOL bit to allow the following write(s) to the SSPBUF register to complete successfully.

When the application software is expecting to receive valid data, the SSPBUF should be read before the next byte of data to transfer is written to the SSPBUF. The Buffer Full bit, BF of the SSPSTAT register, indicates when SSPBUF has been loaded with the received data (transmission is complete). When the SSPBUF is read, the BF bit is cleared. This data may be irrelevant if the SPI is only a transmitter. Generally, the MSSP interrupt is used to determine when the transmission/reception has completed. If the interrupt method is not going to be used, then software polling can be done to ensure that a write collision does not occur.

The SSPSR is not directly readable or writable and can only be accessed by addressing the SSPBUF register. Additionally, the SSPSTAT register indicates the various Status conditions.

FIGURE 30-5: SPI MASTER/SLAVE CONNECTION

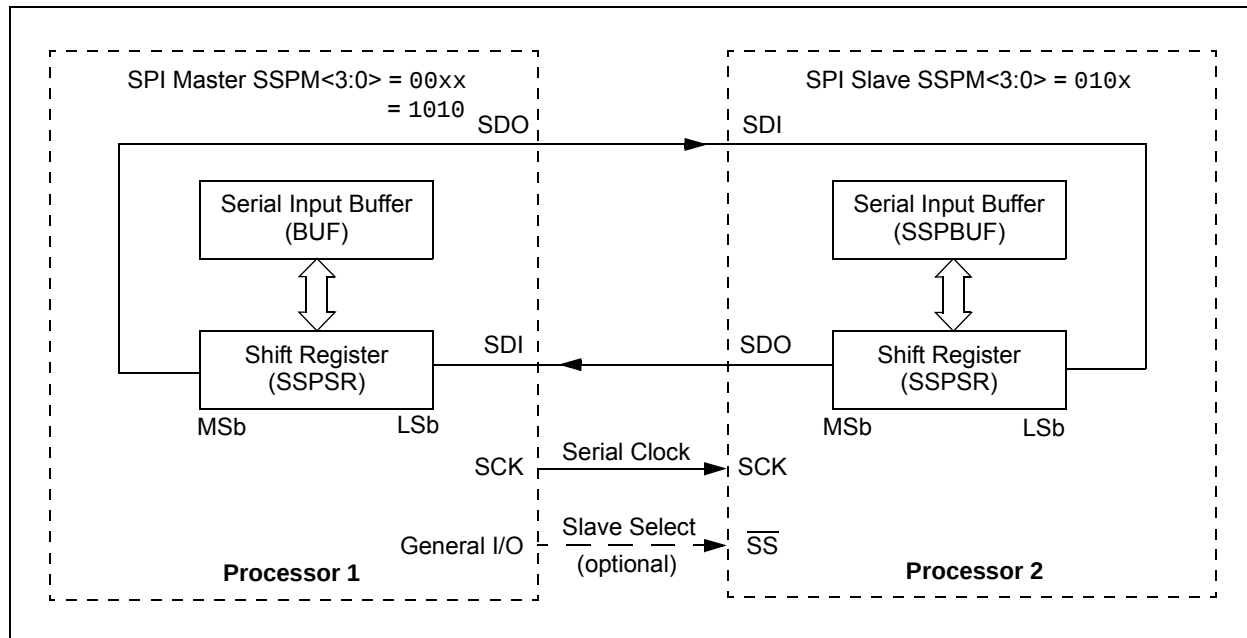
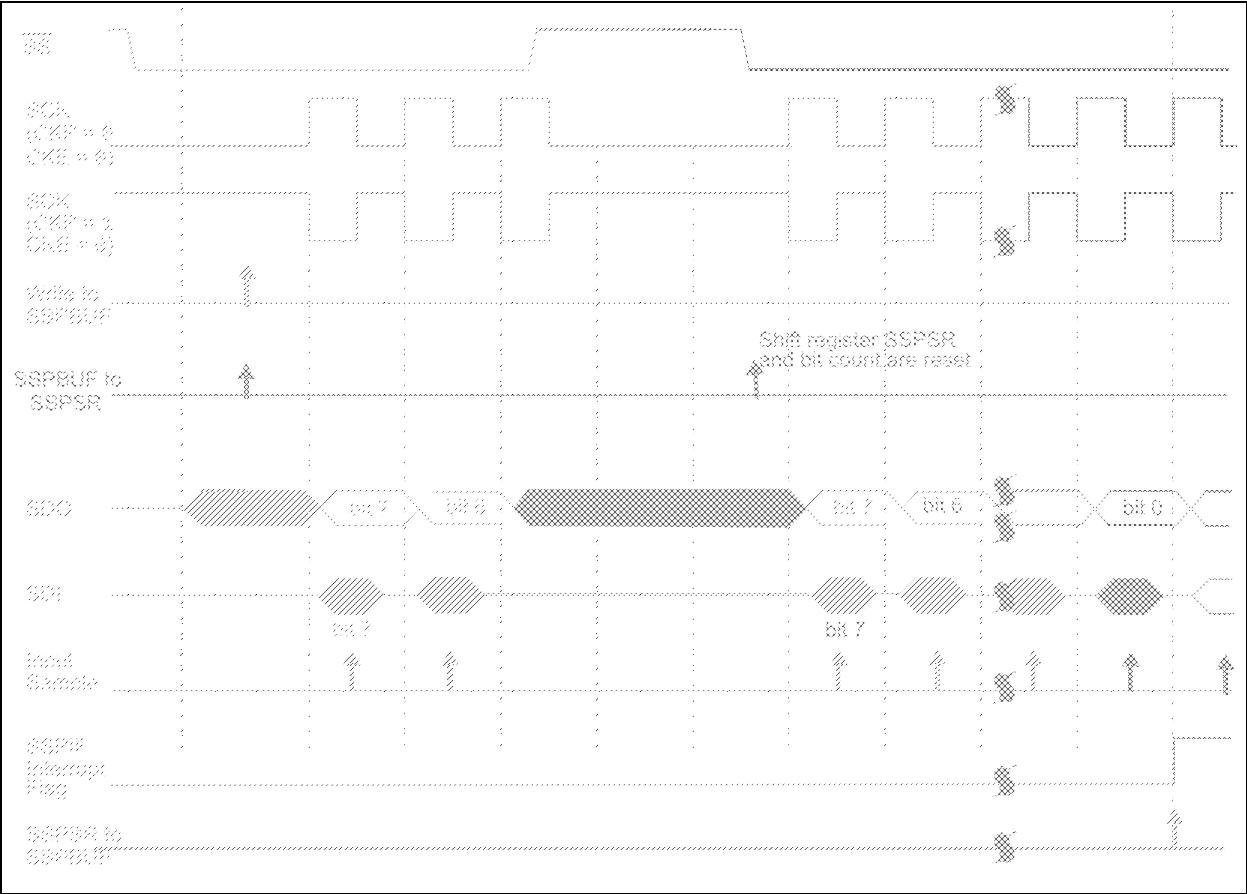


FIGURE 30-8: SLAVE SELECT SYNCHRONOUS WAVEFORM



30.4 I²C MODE OPERATION

All MSSP I²C communication is byte oriented and shifted out MSb first. Six SFR registers and two interrupt flags interface the module with the PIC[®] microcontroller and user software. Two pins, SDA and SCL, are exercised by the module to communicate with other external I²C devices.

30.4.1 BYTE FORMAT

All communication in I²C is done in 9-bit segments. A byte is sent from a master to a slave or vice-versa, followed by an Acknowledge bit sent back. After the eighth falling edge of the SCL line, the device outputting data on the SDA changes that pin to an input and reads in an acknowledge value on the next clock pulse.

The clock signal, SCL, is provided by the master. Data is valid to change while the SCL signal is low, and sampled on the rising edge of the clock. Changes on the SDA line while the SCL line is high define special conditions on the bus, explained below.

30.4.2 DEFINITION OF I²C TERMINOLOGY

There is language and terminology in the description of I²C communication that have definitions specific to I²C. That word usage is defined below and may be used in the rest of this document without explanation. This table was adapted from the Philips I²C specification.

30.4.3 SDA AND SCL PINS

Selection of any I²C mode with the SSPEN bit set, forces the SCL and SDA pins to be open-drain. These pins should be set by the user to inputs by setting the appropriate TRIS bits.

Note 1: Data is tied to output zero when an I²C mode is enabled.

2: Any device pin can be selected for SDA and SCL functions with the PPS peripheral. These functions are bidirectional. The SDA input is selected with the SSPDATPPS registers. The SCL input is selected with the SSPCLKPPS registers. Outputs are selected with the RxyPPS registers. It is the user's responsibility to make the selections so that both the input and the output for each function is on the same pin.

30.4.4 SDA HOLD TIME

The hold time of the SDA pin is selected by the SDAHT bit of the SSPCON3 register. Hold time is the time SDA is held valid after the falling edge of SCL. Setting the SDAHT bit selects a longer 300 ns minimum hold time and may help on buses with large capacitance.

TABLE 30-2: I²C BUS TERMS

TERM	Description
Transmitter	The device which shifts data out onto the bus.
Receiver	The device which shifts data in from the bus.
Master	The device that initiates a transfer, generates clock signals and terminates a transfer.
Slave	The device addressed by the master.
Multi-master	A bus with more than one device that can initiate data transfers.
Arbitration	Procedure to ensure that only one master at a time controls the bus. Winning arbitration ensures that the message is not corrupted.
Synchronization	Procedure to synchronize the clocks of two or more devices on the bus.
Idle	No master is controlling the bus, and both SDA and SCL lines are high.
Active	Any time one or more master devices are controlling the bus.
Addressed Slave	Slave device that has received a matching address and is actively being clocked by a master.
Matching Address	Address byte that is clocked into a slave that matches the value stored in SSPADD.
Write Request	Slave receives a matching address with R/W bit clear, and is ready to clock in data.
Read Request	Master sends an address byte with the R/W bit set, indicating that it wishes to clock data out of the Slave. This data is the next and all following bytes until a Restart or Stop.
Clock Stretching	When a device on the bus hold SCL low to stall communication.
Bus Collision	Any time the SDA line is sampled low by the module while it is outputting and expected high state.

31.4.1 AUTO-BAUD DETECT

The EUSART module supports automatic detection and calibration of the baud rate.

In the Auto-Baud Detect (ABD) mode, the clock to the BRG is reversed. Rather than the BRG clocking the incoming RX signal, the RX signal is timing the BRG. The Baud Rate Generator is used to time the period of a received 55h (ASCII “U”) which is the Sync character for the LIN bus. The unique feature of this character is that it has five rising edges including the Stop bit edge.

Setting the ABDEN bit of the BAUDCON register starts the auto-baud calibration sequence. While the ABD sequence takes place, the EUSART state machine is held in Idle. On the first rising edge of the receive line, after the Start bit, the SPBRG begins counting up using the BRG counter clock as shown in Figure 31-6. The fifth rising edge will occur on the RX pin at the end of the eighth bit period. At that time, an accumulated value totaling the proper BRG period is left in the SPBRGH, SPBRGL register pair, the ABDEN bit is automatically cleared and the RCIF interrupt flag is set. The value in the RCREG needs to be read to clear the RCIF interrupt. RCREG content should be discarded. When calibrating for modes that do not use the SPBRGH register the user can verify that the SPBRGL register did not overflow by checking for 00h in the SPBRGH register.

The BRG auto-baud clock is determined by the BRG16 and BRGH bits as shown in Table 31-6. During ABD, both the SPBRGH and SPBRGL registers are used as a 16-bit counter, independent of the BRG16 bit setting. While calibrating the baud rate period, the SPBRGH

and SPBRGL registers are clocked at 1/8th the BRG base clock rate. The resulting byte measurement is the average bit time when clocked at full speed.

Note 1: If the WUE bit is set with the ABDEN bit, auto-baud detection will occur on the byte following the Break character (see **Section 31.4.3 “Auto-Wake-up on Break”**).

2: It is up to the user to determine that the incoming character baud rate is within the range of the selected BRG clock source. Some combinations of oscillator frequency and EUSART baud rates are not possible.

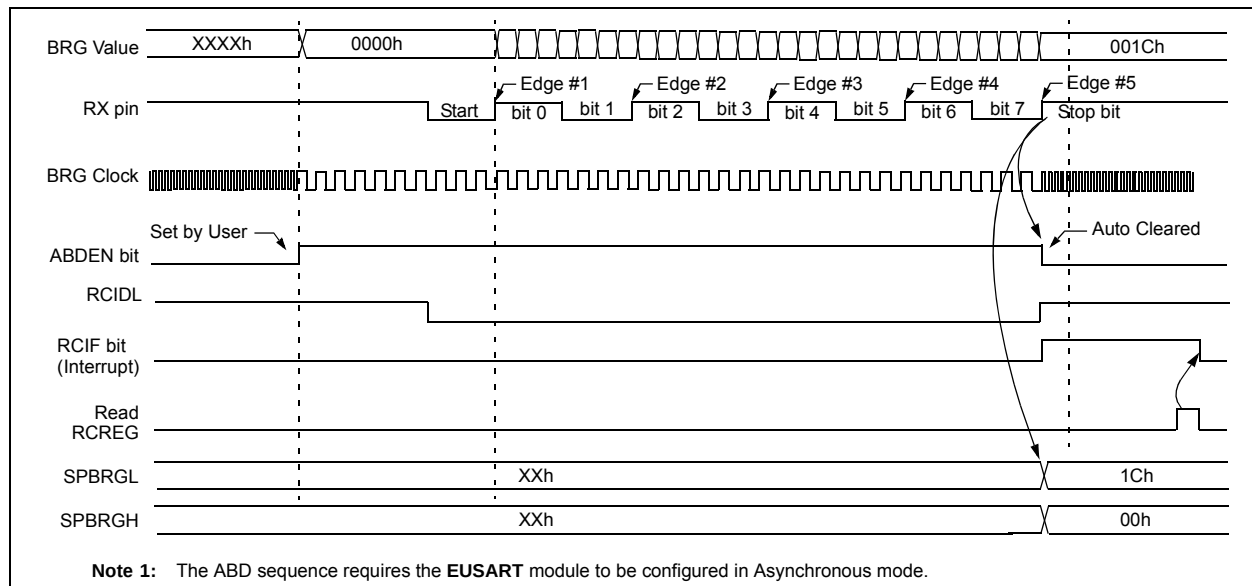
3: During the auto-baud process, the auto-baud counter starts counting at one. Upon completion of the auto-baud sequence, to achieve maximum accuracy, subtract 1 from the SPBRGH:SPBRGL register pair.

TABLE 31-6: BRG COUNTER CLOCK RATES

BRG16	BRGH	BRG Base Clock	BRG ABD Clock
0	0	Fosc/64	Fosc/512
0	1	Fosc/16	Fosc/128
1	0	Fosc/16	Fosc/128
1	1	Fosc/4	Fosc/32

Note: During the ABD sequence, SPBRGL and SPBRGH registers are both used as a 16-bit counter, independent of the BRG16 setting.

FIGURE 31-6: AUTOMATIC BAUD RATE CALIBRATION



PIC16(L)F1713/6

CALL Call Subroutine

Syntax: [*label*] CALL *k*

Operands: $0 \leq k \leq 2047$

Operation: (PC)+1 → TOS,
k → PC<10:0>,
(PCLATH<6:3>) → PC<14:11>

Status Affected: None

Description: Call Subroutine. First, return address (PC + 1) is pushed onto the stack. The 11-bit immediate address is loaded into PC bits <10:0>. The upper bits of the PC are loaded from PCLATH. CALL is a 2-cycle instruction.

CALLW Subroutine Call With W

Syntax: [*label*] CALLW

Operands: None

Operation: (PC) + 1 → TOS,
(W) → PC<7:0>,
(PCLATH<6:0>) → PC<14:8>

Status Affected: None

Description: Subroutine call with W. First, the return address (PC + 1) is pushed onto the return stack. Then, the contents of W is loaded into PC<7:0>, and the contents of PCLATH into PC<14:8>. CALLW is a 2-cycle instruction.

CLRF Clear f

Syntax: [*label*] CLRF *f*

Operands: $0 \leq f \leq 127$

Operation: 00h → (f)
1 → Z

Status Affected: Z

Description: The contents of register 'f' are cleared and the Z bit is set.

CLRW Clear W

Syntax: [*label*] CLRW

Operands: None

Operation: 00h → (W)
1 → Z

Status Affected: Z

Description: W register is cleared. Zero bit (Z) is set.

CLRWDTClear Watchdog Timer

Syntax: [*label*] CLRWDTClear Watchdog Timer

Operands: None

Operation: 00h → WDT
0 → WDT prescaler,
1 → $\overline{TO}$
1 → $\overline{PD}$

Status Affected: $\overline{TO}$, $\overline{PD}$

Description: CLRWDTClear Watchdog Timer. It also resets the prescaler of the WDT. Status bits $\overline{TO}$ and $\overline{PD}$ are set.

COMF Complement f

Syntax: [*label*] COMF *f*,*d*

Operands: $0 \leq f \leq 127$
d ∈ [0,1]

Operation: ($\bar{f}$) → (destination)

Status Affected: Z

Description: The contents of register 'f' are complemented. If 'd' is '0', the result is stored in W. If 'd' is '1', the result is stored back in register 'f'.

DECF Decrement f

Syntax: [*label*] DECF *f*,*d*

Operands: $0 \leq f \leq 127$
d ∈ [0,1]

Operation: (f) - 1 → (destination)

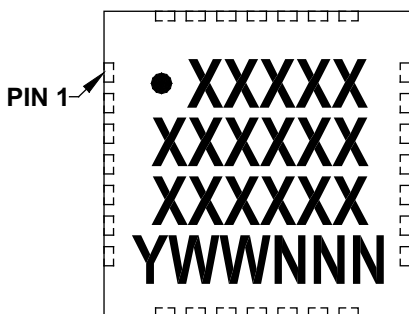
Status Affected: Z

Description: Decrement register 'f'. If 'd' is '0', the result is stored in the W register. If 'd' is '1', the result is stored back in register 'f'.

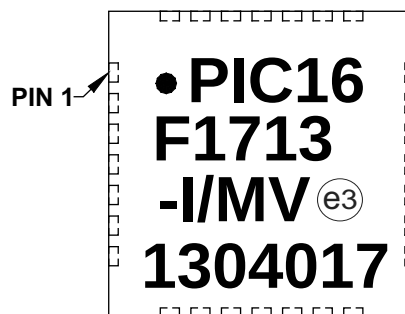
PIC16(L)F1713/6

Package Marking Information (Continued)

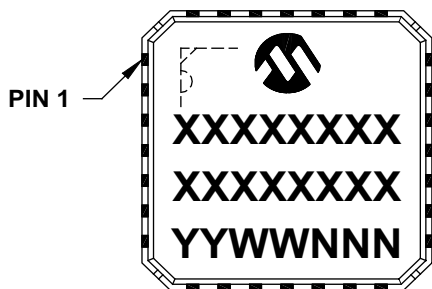
28-Lead UQFN (4x4x0.5 mm)



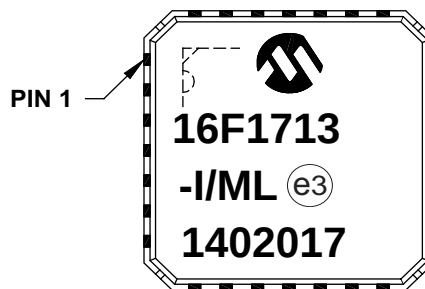
Example



28-Lead QFN (6x6x0.9 mm)



Example

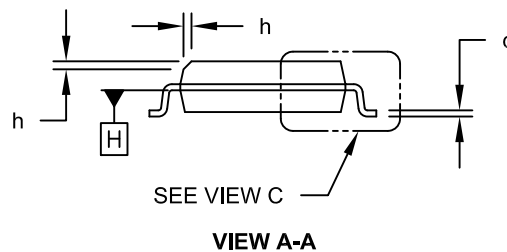
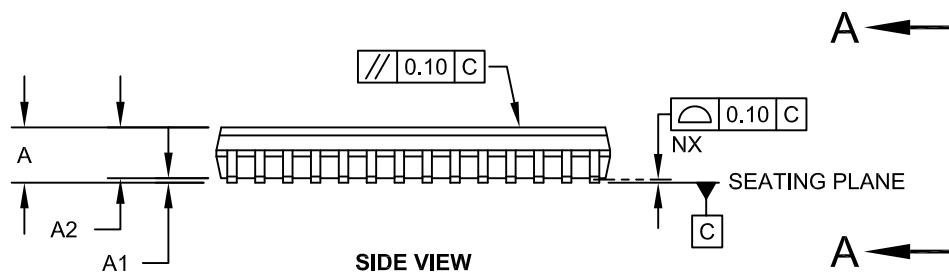
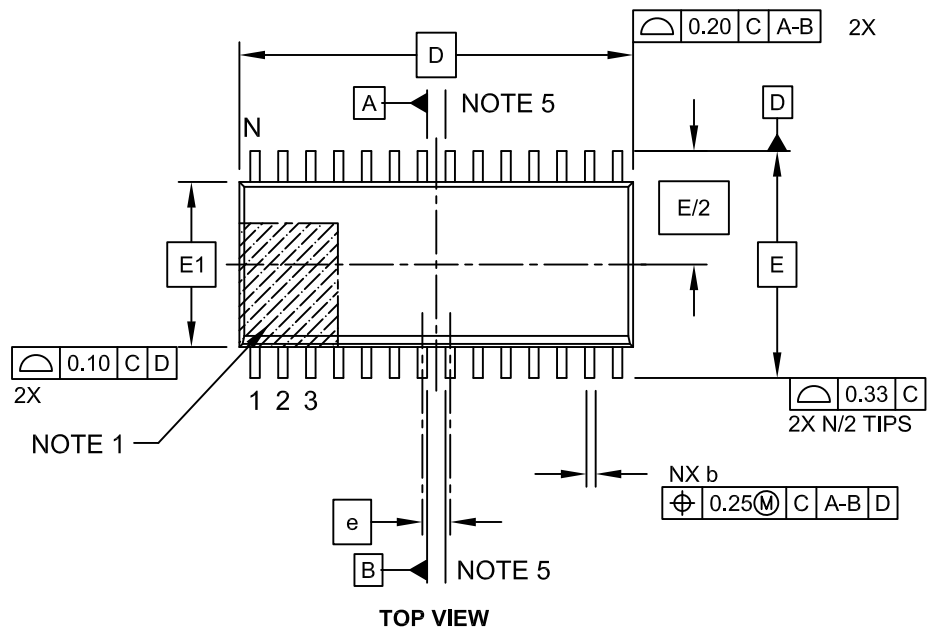


Legend:	XX...X	Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week '01')
	NNN	Alphanumeric traceability code
	(e3)	Pb-free JEDEC® designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator (e3) can be found on the outer packaging for this package.

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

28-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



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